

Stack up

Layer NO.	Hole layer design	Name	Material	Thickness (Mil)	Thickness (um)
			SolderMask	min0.4	25.00
1	R04350B->Core	Top	Hoz + Plating	0.80	20.32
			Core	4.00	101.60
2	IT-180A->PP2113 RC59	L2	Copper foil (0.5oz)	0.60	15.24
			PP	3.70	93.98
3	IT-180A->Core	L3	Copper foil (0.5oz)	0.60	15.24
			Core	4.00	101.60
4	IT-180A->PP2113 RC59	L4	Copper foil (0.5oz)	0.60	15.24
			PP	3.70	93.98
5	IT-180A->PP1506 RC53	L5	Copper foil (1.0oz)	0.80	20.32
			PP	7.00	177.80
6	M6G->PP3313 RC54	L6	Copper foil (1.0oz)	0.80	20.32
			PP	3.50	88.90
7	R04350B->Core		Core	20.00	508.00
		BOT	Hoz + Plating	0.80	20.32
			SolderMask	min0.4	25.00
Board Thickness=1.35+/-0.135mm				52.87	1342.86